



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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△ MATERIALS:
HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0
SHIELD - 0.101" THICK, C26800 BRASS PREPLATED WITH 30μINCH MIN SEMI-BRIGHT
NICKEL - SOLDER TABS POST DIPPED WITH 100μINCH MIN SAC SOLDER
MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50μINCH MIN OVERALL
NICKEL UNDERPLATE WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE.
SOLDER TAILS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
LIGHT EMITTING DIODEDIP - DIFFUSED EPOXY LENS, 0207 X 0.020" CARBON STEEL
WIREFRAME LEADS PRE-PLATED WITH 80μINCH SILVER OVER 40μINCH NICKEL
UNDERPLATE OVER 40μINCH COPPER UNDERPLATE. POST-PLATED WITH 100μINCH
MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.

△ RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB
PART F.

△ MAGNETICS
-IMPEDANCE: 100 OHMS
-TURNS RATIO (CHIP CABLE): TX = 1, RX = 11
-OPEN CIRCUIT INDUCTANCE (OCL): 350μH MIN @100kHz, 0.1VRMS,
8mADC BIAS FROM -40°C TO +85°C, TX AND RX
-PERFORMANCE @ 25°C:
INSERTION LOSS (IL): 11dB MAX FROM 0.5MHz TO 100MHz
RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
18-20.0LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz
12dB MIN FROM 60.1MHz TO 80MHz
CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
33-20.0LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz
COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
-ISOLATION VOLTAGE:2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF
500V/SEC.

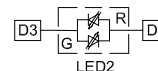
4. OPERATING TEMPERATURE: FROM -40° TO +85°C.

△ INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION. THE MAGNETICS ARE
SYMMETRIC, AND SUPPORT AUTO-MDI/MDIX.

△ LEADS ARE DRIVEN WITH CONSTANT CURRENT AT APPROX 20 mA
LED COLOR: DOMINANT WAVELENGTH (AD): GREEN 568 nm TYP @ IF=20 mA
FORWARD VOLTAGE (VF): GREEN 2.2V TYP @ IF=20 mA
LED COLOR: DOMINANT WAVELENGTH (AD): RED 640 nm TYP @ IF=20 mA
FORWARD VOLTAGE (VF): RED 2.2V TYP @ IF=20 mA




△ TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND
AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.

8. THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS, PREHEAT
TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE
SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.



R1-R4 = 75 OHMS, 1/16 W RESISTORS



GREEN/RED		GREEN/RED		6-6605457-4	
LED1 		LED2 		PART NUMBER	
MW A. FERNANDEZ-RODRIGUEZ D. FAROLE GAMESA				TE Connectivity	
D. FAROLE GAMESA 108-21010 APPLICATION SPEC		1X1 MAG45(TM), MODULAR JACK, 42NPET1 INDUSTRIAL TEMP SPECIMATIC, 415ETP1 MAGNETIC COIL, SHIELDED, RECOILING CAPACITOR, B-GNOSTIC LEADS			
WEIGHT —		SIZE A1 00779		C=6605457	
CUSTOMER DRAWING		SOLD NITS		SHEET 1 of 1 REV C	